



# SOT387-3

plastic shrink quad flat package; 128 leads (lead length 1.6 mm); body 14 x 20 x 2.72 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	SQFP128
Package type industry code	SQFP128
Package style descriptive code	SQFP (shrink quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	25-2-2003

Table 1. Package summary

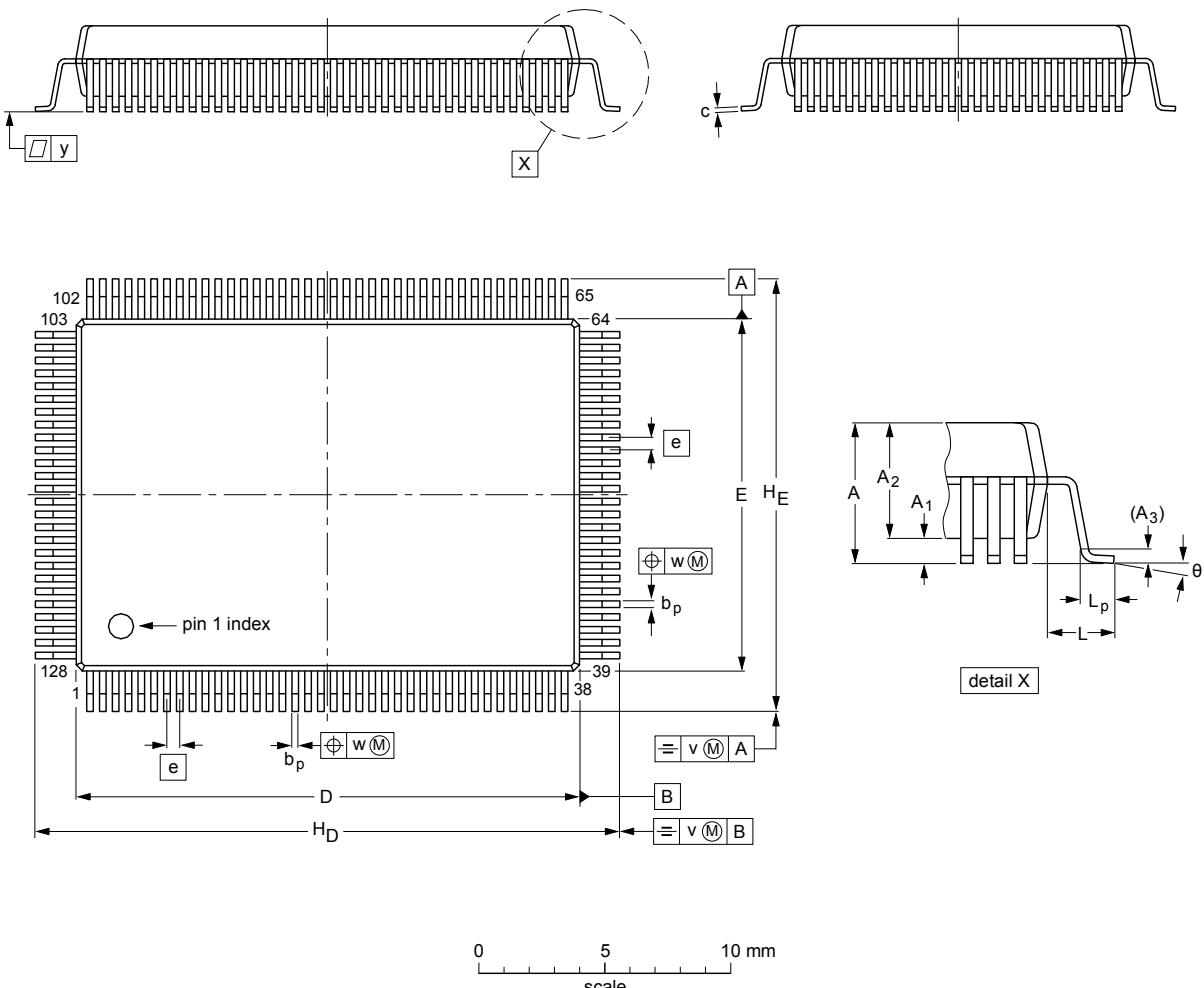
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	3.4	3.4	mm
A <sub>2</sub>	package height	2.5	-	2.72	2.9	mm
n <sub>2</sub>	actual quantity of termination	-	-	128	-	



## 2. Package outline

SQFP128: plastic shrink quad flat package;  
128 leads (lead length 1.6 mm); body 14 x 20 x 2.72 mm

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### DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	θ
mm	3.4	0.25	2.9	0.25	0.27	0.23	20.1	19.9	0.5	23.35	17.35	1.6	1.03	0.2	0.08	0.08	7° 0°

### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

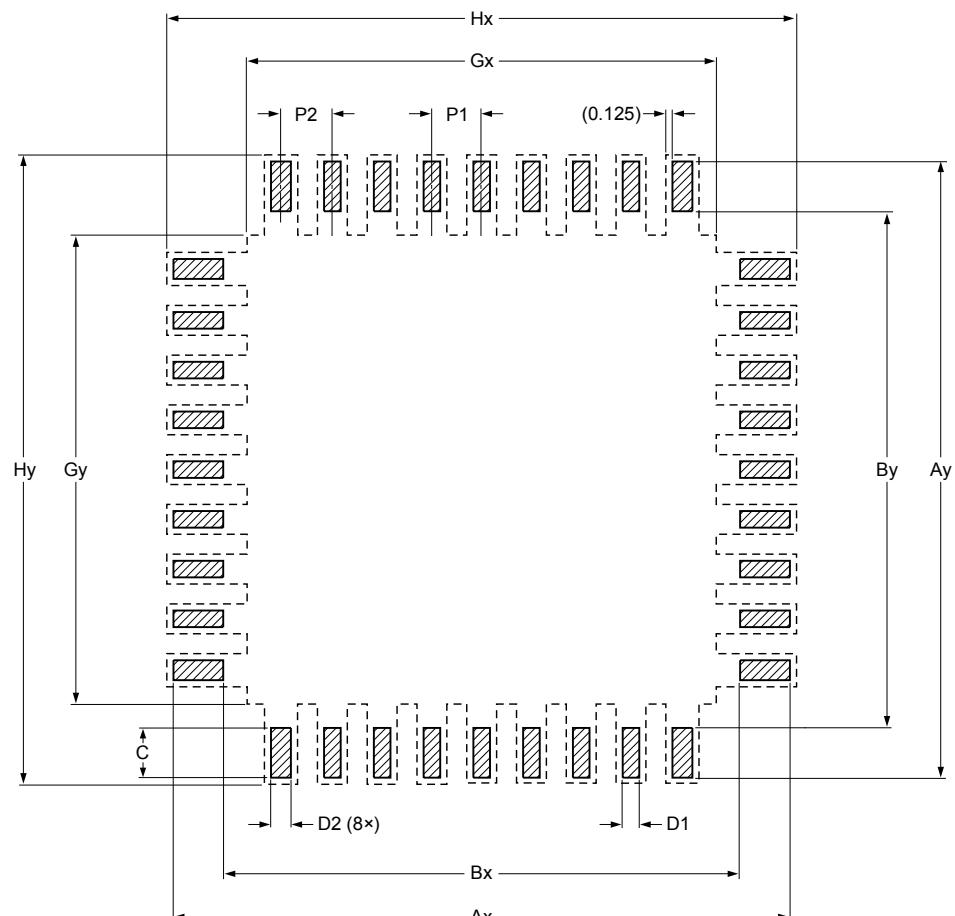
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT387-3						98-03-27 03-02-25

Fig. 1. Package outline SQFP128 (SOT387-3)

### 3. Soldering

Footprint information for reflow soldering of SQFP128 package

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solder land

----- occupied area

#### DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	23.900	17.900	20.900	14.900	1.500	0.280	0.400	20.500	14.500	24.150	18.150

sot387-3\_fr

Fig. 2. Reflow soldering footprint for SQFP128 (SOT387-3)

## 4. Legal information

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